

C1206X629D8TACTU

Aliases (C1206X629D8TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 6.2 pF, ± 0.5 pF, 10 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206



Click [here](#) for the 3D model.

General Information

Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	17 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	6.2 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	± 0.5 pF
Voltage DC	10 VDC
Dielectric Withstanding Voltage	25 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Dimensions

Chip Size	1206
L	3.3mm ± 0.4 mm
W	1.6mm ± 0.35 mm
T	0.78mm ± 0.20 mm
S	1.5mm MIN
B	0.6mm ± 0.25 mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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